

MECHANICAL CASE OUTLINE

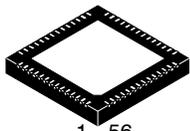
PACKAGE DIMENSIONS

ON Semiconductor®

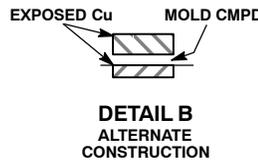
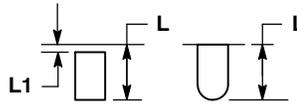
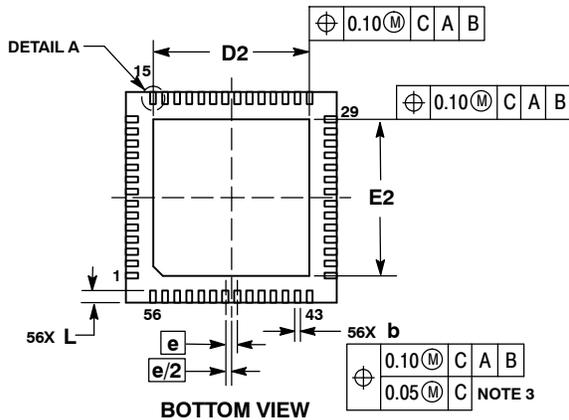
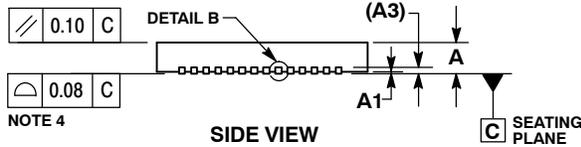
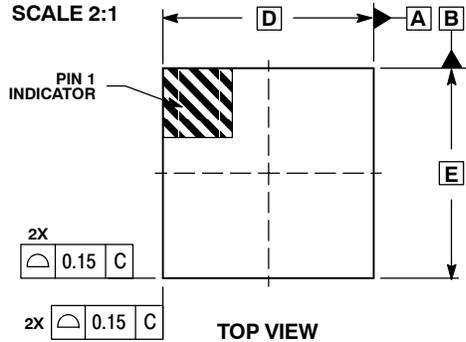


WQFN56 7x7, 0.4P
CASE 510BD
ISSUE O

DATE 29 JAN 2013



1 56
SCALE 2:1

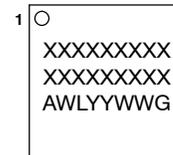


NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO THE PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.80
A1	0.00	0.05
A3	0.20 REF	
b	0.15	0.25
D	7.00 BSC	
D2	5.10	5.30
E	7.00 BSC	
E2	5.10	5.30
e	0.40 BSC	
L	0.30	0.50
L1	0.00	0.15

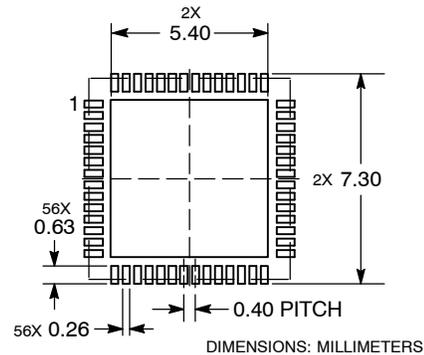
GENERIC MARKING DIAGRAM*



- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	WQFN56 7X7, 0.40P	PAGE 1 OF 2

